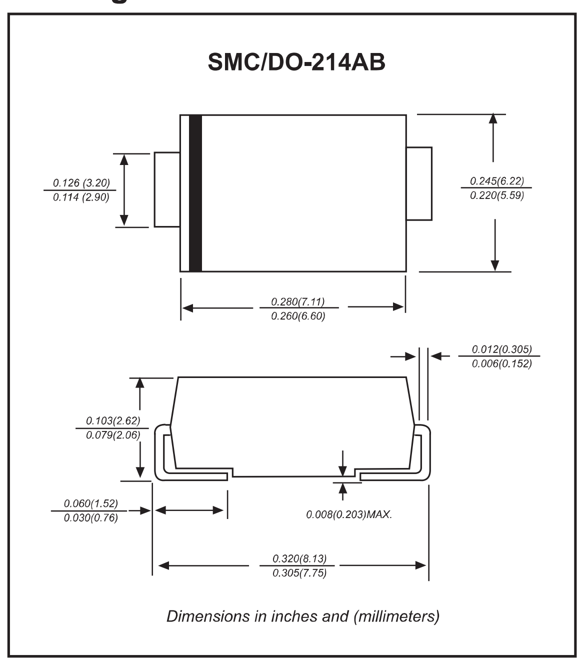
S3AC THRU S3MC

3.0A Surface Mount General Purpose Rectifiers - 50V-1000V

Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Low reverse leakage
- Built-in strain relief,ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 260°C/10 seconds at terminals
- Glass passivated chip junction
- Compliant to RoHS Directive 2011/65/EU

Package outline



Mechanical data

- **Case**: JEDEC DO-214AB molded plastic body
- **Terminals**: Solder plated, solderable per MIL-STD-750, Method 2026
- **Polarity**: Color band denotes cathode end
- **Mounting Position**: Any

Maximum ratings and Electrical Characteristics (AT T_A=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	I_O			3.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			80	A
Reverse current	V_R = V_{RRM} T_A = 25°C	I_R			5.0	μA
	V_R = V_{RRM} T_A = 100°C				50	
Thermal resistance	Junction to ambient NOTE 1	$R_{θJA}$		40		°C/W
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		40		pF
Storage temperature		T_{STG}	-55		+150	°C

Note: 1.P.C.B. mounted with 2.0x2.0″(5.0x5.0cm) copper pad areas

SYMBOLS	V_{RRM} *1 (V)	V_{RMS} *2 (V)	V_R *3 (V)	V_F *4 (V)	Operating temperature T_J, (°C)
S3AC	50	35	50	1.10	-55 to +150
S3BC	100	70	100		
S3DC	200	140	200		
S3GC	400	280	400		
S3JC	600	420	600		
S3KC	800	560	800		
S3MC	1000	700	1000		

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage@I_F=3.0A

Rating and characteristic curves

FIG. 1- FORWARD CURRENT DERATING CURVE

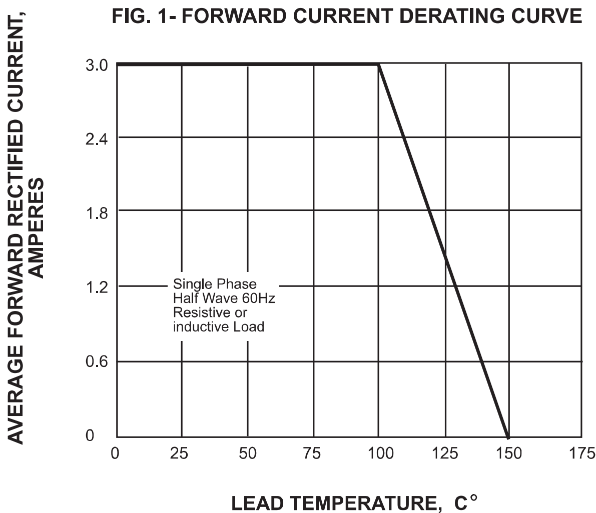


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

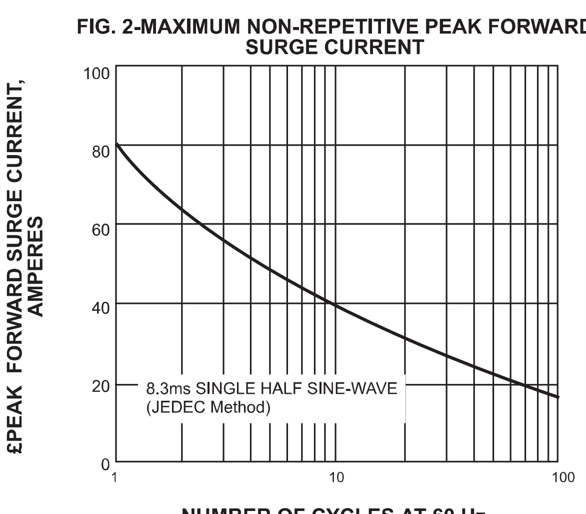


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

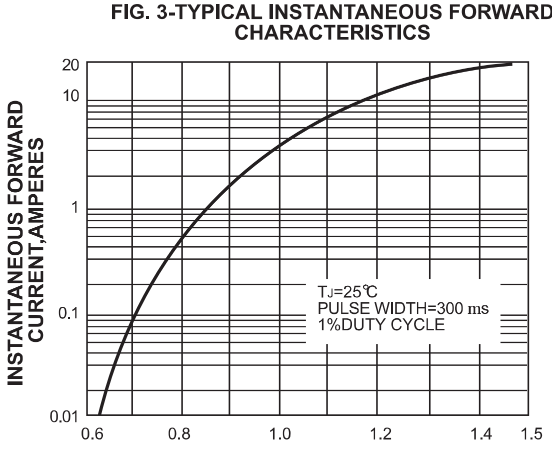


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

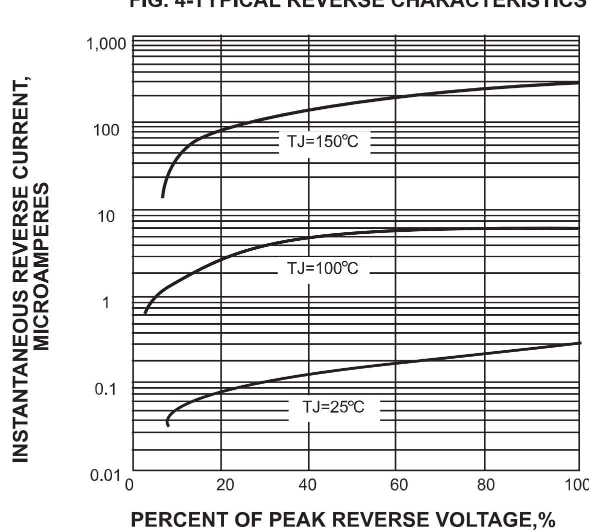


FIG. 5-TYPICAL JUNCTION CAPACITANCE

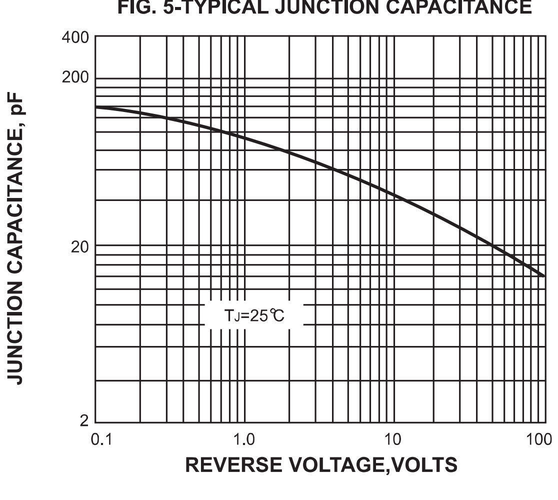
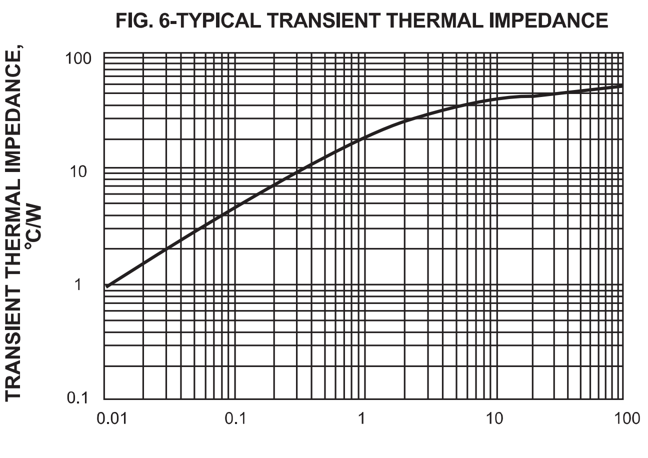


FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



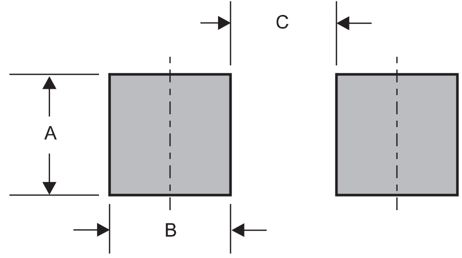
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode	1 [outline] 2	1 [diode symbol] 2

Marking

Type number	Marking code
S3AC	S3A
S3BC	S3B
S3DC	S3D
S3GC	S3G
S3JC	S3J
S3KC	S3K
S3MC	S3M

Suggested solder pad layout



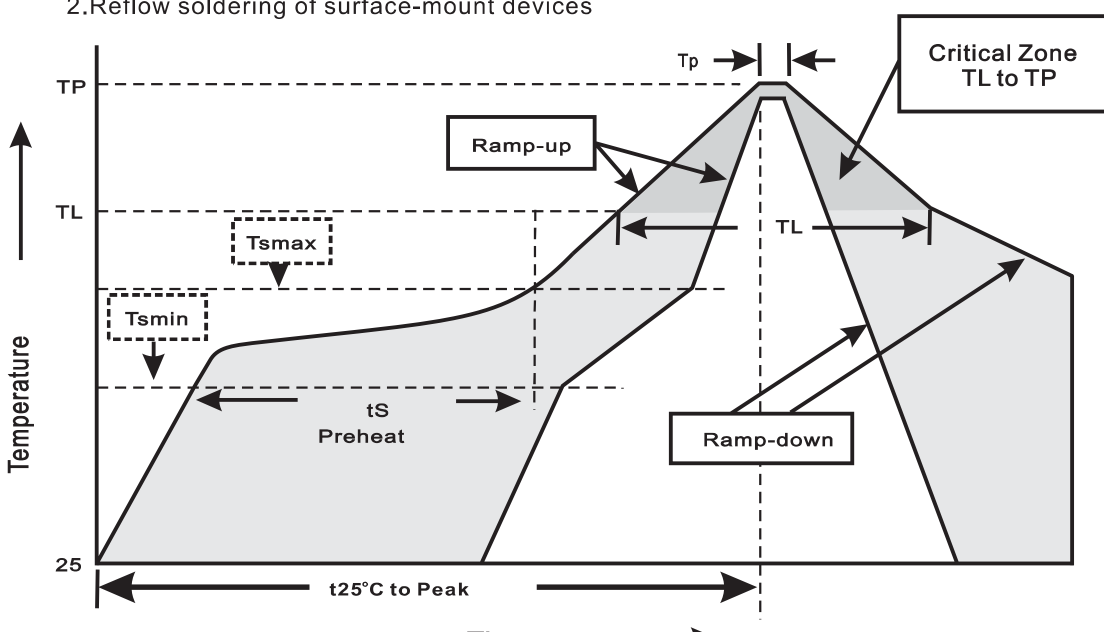
Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMC	0.132 (3.30)	0.100 (2.50)	0.176(4.40)

Suggested thermal profiles for soldering processes

1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%

2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(t_s)	150°C 200°C 60~120sec
Tsmax to T_L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes